



## Material Content Data Sheet



<b>Sales Product Name</b>		IKB15N60T		<b>Issued</b>		4. July 2019		
<b>MA#</b>		MA005342016						
<b>Package</b>		PG-TO263-3-2		<b>Weight*</b>		1558.16 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	0.871	0.06	0.06	559	559
chip_2	inorganic material	silicon	7440-21-3	1.597	0.10	0.10	1025	1025
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		59	
	non noble metal	iron	7439-89-6	0.304	0.02		195	
wire	non noble metal	copper	7440-50-8	304.026	19.51	19.54	195118	195372
	non noble metal	aluminium	7429-90-5	3.224	0.21	0.21	2069	2069
encapsulation	organic material	carbon black	1333-86-4	10.305	0.66		6613	
	plastics	epoxy resin	-	113.353	7.27		72748	
leadfinish	inorganic material	silicondioxide	60676-86-0	563.328	36.16	44.09	361533	440894
	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6197	6197
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	147	148
solder	non noble metal	tin	7440-31-5	0.056	0.00		36	
	noble metal	silver	7440-22-4	0.070	0.00		45	
heatspreader	non noble metal	lead	7439-92-1	2.672	0.17	0.17	1715	1796
	inorganic material	phosphorus	7723-14-0	0.165	0.01		106	
*deviation	non noble metal	iron	7439-89-6	0.548	0.04		352	
	non noble metal	copper	7440-50-8	547.666	35.15	35.20	351482	351940
Sum in total:						100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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